

PRODUCT DATA SHEET

EPG-1020

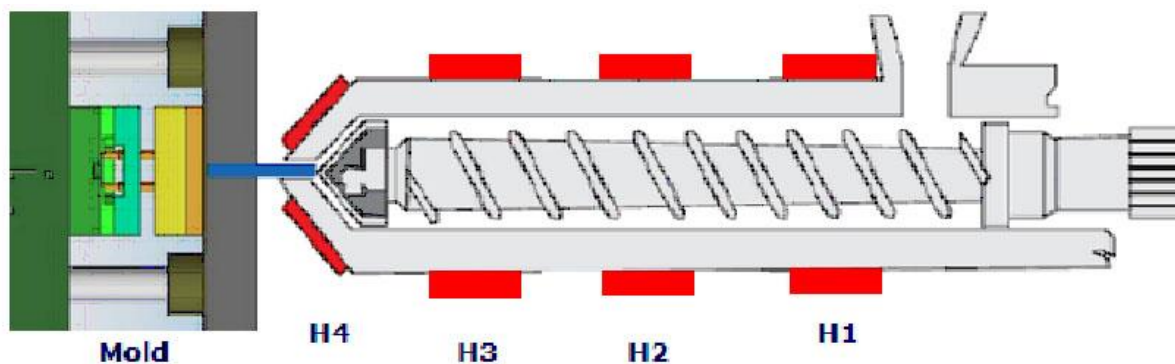
■ Description : PC+GF20% , with high stiffness, high modulus, high viscosity and easy mold release

■ Application : Electrical and Electronics Housing , building material etc.,

General properties	Typical value	Unit	Test method
Specific Gravity	1.34	g/cm ³	ISO 1183
Melt flow rate ,@300°C, 1.2 kgf	5.0	g/10min	ISO 1133
Mold Shrinkage	0.3 ~ 0.5	% (3~5/1,000)	Polylex Method
Mechanical properties			
Izod impact strength, 1/8"notched @+23°C	10	KJ / m ²	ISO 180
Tensile stress, @ yield, 50 mm/min	90	MPa	ISO 527
Tensile strain, @ break, 50 mm/min	3	%	ISO 527
Flexural Strength, @ 2mm/min	150	MPa	ISO 178
Flexural Modulus, @ 2mm/min	5,200	MPa	ISO 178
Thermal properties			
Heat Deflection Temperature @ 1.86MPa, 4mm	140	°C	ISO 75
Flammability			
UL-94 method	1.6	mm	V-2

* The above values are for the representatives

PROCESSING GUIDE of EPG-1020



Parameter Injection Molding		Value	Unit
Drying Temperature		°C	120
Drying Time		HR	2 ~ 3
Maximum moisture content		%	0.02
Melt Temperature		°C	290 ~ 300
Cylinder Temperature	H4	°C	290 ~ 300
	H3	°C	280 ~ 290
	H2	°C	270 ~ 280
	H1	°C	250 ~ 260
Mold Temperature		°C	80 ~ 120
Back Pressure		MPa	0.3 ~ 0.7
Screw rotating speed		rpm	20 ~ 100